82S12-F.N • 82S112-F.N

DESCRIPTION

Data is stored in a single storage matrix which is addressed via 2 independent sets of address inputs, designated respectively as Port A and Port B.

Data can be read from memory via either Port A or B, through their respective output sets. However, input data (latched on the leading edge of write enable in the input data latches) is written only in memory locations specified by the address on Port A, regardless of Port B.

When both Port addresses are equal, data from the same location can be read in either or both Port output sets by means of output select lines S_A and S_B . During Write, new data stored in memory is immediately transferred on both Port output sets.

When both Port addresses are different, 2 different locations can be simultaneously read from memory. It is also possible to simultaneously read through Port B while writing new input data through Port A by utilizing the "A_N" address to specify the location of the word to be written, and the "B_N" address to specify the word to be read.

Both devices are ideally suited for high speed accumulator and buffer memories, and can be readily expanded to form larger arrays by means of their output select and write enable lines.

Both the 82S12 and 82S112 are available over the limited temperature range of +10° C to +75° C. Over this temperature range, specify N82S12/82S112F,N.

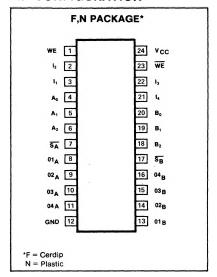
FEATURES

- Address access time: 40ns max
- Write cycle time: 65ns max
- Power dissipation: 8.5mW/bit typ
- Input loading: -250μA max
- On-chip address decoding
- Output options: 82S12 Open collector 82S112 Tri-state
- Non-inverting outputs
- Input data latches
- Two write enable lines
- Separate output enable lines
- · Output follows data input during write
- TTL compatible

APPLICATIONS

- Buffer memory
- Accumulator register
- Data routing/shifting
- ALU control
- Multiprocessor memory management
- Bandwidth increase by multi-operand fetch
- Communication controllers
- I/O data packing/unpacking
- Large FIFO memories

PIN CONFIGURATION



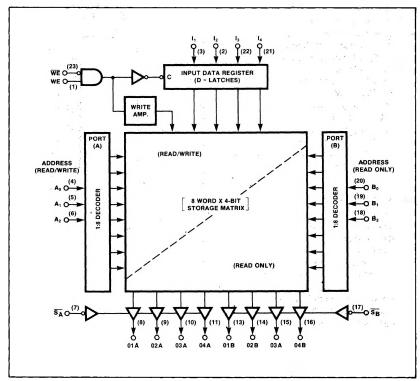
TRUTH TABLE

			}			PORT	82S12		825	112
MODE	WE	WE	IN	SA	SB	ADDRESS	(ON)A	(ON)B	(ON)A	(ON)B
Disabled				1	1	Х	1	1	Hi-Z	Hi-Z
	0	x		0	1		Stored Data	1	Stored Data	Hi-Z
Read		r	x	1	0	A = B	1	Stored Data	Hi-Z	Stored Data
	x			0	0		Stored Data	Stored Data	Stored Data	Stored Data
		1		0	1		[AN]	1	[AN]	Hi-Z
	l			1	0	A≠B	1	[BN]	Hi-Z	(BN)
			Ĺ	0	0	İ	[AN]	(BN)	[AN]	[B _N]
				1	1		1	1	Hi-Z	Hi-Z
Write	ł			0	1	A = B	IN	1	IN	Hi-Z
	1	0	1/0	1	0		1	IN	Hi-Z	IN
				0	0		IN	IN	IN	IN
	l			1	1		1	1	Hi-Z	Hi-Z
	ł		}	0	1	A≠B	IN	1	IN	Hi-Z
	1		l	1	0	l	1	[BN]	Hi-Z	[B _N]
	(1	i	lo	Ιo	1	l IN	гВит	IN	(BNI

X = Don't care

^{|] =} Contents of

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

P	ARAMETER1	RATING	UNIT	
Vcc	Supply voltage	+7	Vdc	
VIN	Input voltage	+5.5	Vdc	
	Output voltage		Vdc	
Voh	High (82S12)	+5.5	o	
Vo	Off-state (82S112)	-+5.5	11.11	
lin	Input current	±30	mA	
lout	Output current	+100	mA	
	Temperature range		•c	
TA	Operating	0 to +75	-	
TSTG	Storage	-65 to +150		

DC ELECTRICAL CHARACTERISTICS $+10^{\circ}$ C \leq T_A \leq 75°C, 4.75V \leq V_{CC} \leq 5.25V

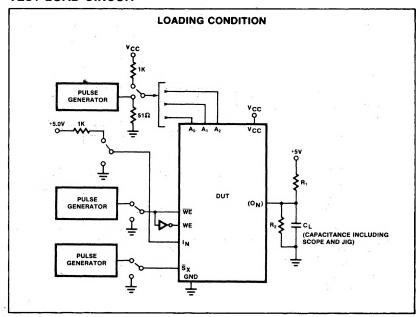
		TEAT COMPLETIONS	82S12			82S112			
P#	ARAMETER1	TEST CONDITIONS	Min	Typ ²	Max	Min	Typ ²	Max	UNIT
VIH VIL VIC	Input voltage High ¹ Low ¹ Clamp ^{1,3}	V _{CC} = 5.25V V _{CC} = 4.75V V _{CC} = 4.75V, I _{IN} = -18mA	2	-0.8	0.85 -1.2	2	-0.8	0.85 -1.2	٧
Vон Vol	Output voltage High1,4 Low1,5	$V_{CC} = 4.75V$ $I_{OH} = -2mA$ $I_{OL} = 9.6mA$		0.35	0.45	2.4	0.35	0.45	٧
Iн IIL	Input current High Low	V _{IN} = 5.5V V _{IN} = 0.45V		1 -10	25 -250		1 -10	25 -250	μΑ
lolk lo(off)	Output current Leakage ⁶ Hi-Z state ⁶ Short circuit ^{3,7}	V _{CC} = 5.25V V _{OUT} = 5.25V V _{OUT} = 5.25V V _{OUT} = 0.45V V _{OUT} = 0V		1	40	-20	1 -1	40 -40 -70	μA μA mA
Icc	Vcc supply current8	V _{CC} = 5.25V		110	160		110	160	mA
Cin Vout	Capacitance Input Output	$V_{CC} = 5.0V$ $V_{IN} = 2.0V$ $V_{OUT} = 2.0V$		5 8			5 8		pF

AC ELECTRICAL CHARACTERISTICS $+10^{\circ}$ C \leq T_A \leq +75° C, 4.75V \leq V_{CC} \leq 5.25V, R₁ = 470 Ω , R₂ = 1k Ω , C_L = 30pF

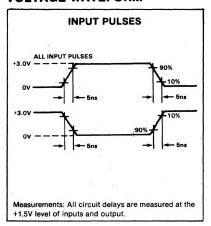
				LIMITS				
l	PARAMETER	то	FROM	Min	Typ ²	Max 40 30	UNIT	
TAA Tse	Access time Address Port select	Output Output	Address Output enable				ns	
T _{SD}	Disable time Port deselect	Output	Output enable			30	ns	
Two	Valid time	Output	Write enable			40	ns	
Twsa Twha	Setup and hold time Setup time Hold time	Write enable	Address	15 5	10 0		ns	
Twsd Twhd	Setup time Hold time	Write enable	Data in	15 10				
Twp	Pulse width Write enable	*		45			ns	

- 1. All voltage values are with respect to network ground terminal. 2. All typical values are at $V_{CC}=5V,\,T_A=25^{\circ}C.$
- 3. Test one at the time.
- Measured with V_{IL} applied to S_X and a logic high stored.
- 5. Measured with a logic low stored. Output sink current is supplied through a resistor to Vcc.
- 6. Measured with VIH applied to Sx.
- 7. Duration of short circuit should not exceed 1 second.
- 8. Icc is measured with all inputs at 4.5V and the outputs open.

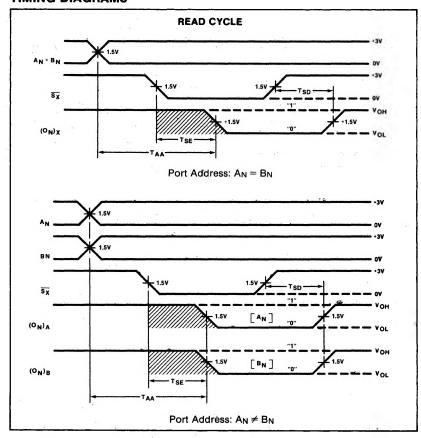
TEST LOAD CIRCUIT



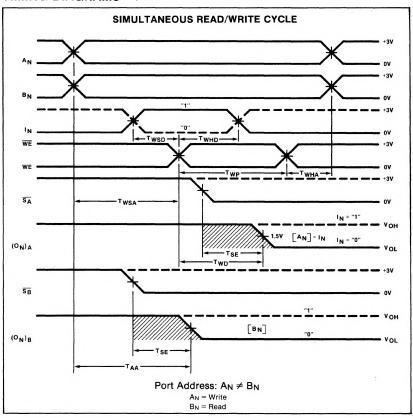
VOLTAGE WAVEFORM

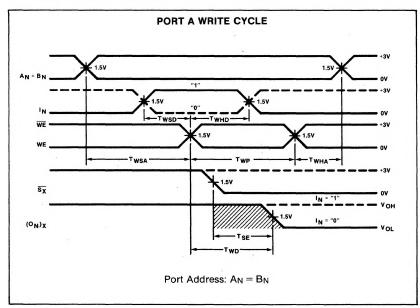


TIMING DIAGRAMS



TIMING DIAGRAMS (Cont'd)





MEMORY TIMING DEFINITIONS

- TSE Delay between beginning of Output Enable low (with Address valid) and when Data Output becomes valid.
- T_{SD} Delay between when Output Enable becomes high and Data Output is in Hi-Z or high state.
- TAA Delay between beginning of valid Address (with Output Enable low) and when Data Output becomes valid.
- TWHD Required delay between end of Write Enable pulse and end of valid Input Data.
- TWP Width of Write Enable pulse.
 TWSA Required delay between beginning of valid Address and begin-
- Twsp ning of Write Enable pulse.
 Required delay between beginning of valid Data Input and end of Write Enable pulse.
- TwD Delay between beginning of Write Enable pulse and when Data Output reflects the Data Input.
- TWHA Required delay between end of Write Enable pulse and end of valid Address.